N-Channel Enhancement Mode MOSFET

BL035N04T-5DL8

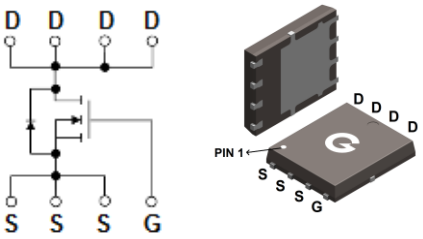
HF

Features

- Ultra-low on-resistance and gate-charge
- HBM: JESD22-A114-B: 1A

Mechanical Data

- Case: PDFN5×6-8L
- Molding Compound: UL Flammability Classification Rating 94V-0
- Terminals: Matte tin-plated leads; solderability-per MIL-STD-202, Method 208



PDFN5×6-8L

Ordering Information

Part Number	Package	Shipping Quantity	Marking Code
BL035N04T-5DL8	PDFN5×6-8L	5000 pcs / Tape & Reel	035N04T

Maximum Ratings (@ T_A = 25°C unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain-to-Source Voltage	V_{DSS}	40	V
Gate-to-Source Voltage	V_{GSS}	±20	V
Continuous Drain Current (T_C = 25°C, Silicon Limited)	I_D	118	A
Continuous Drain Current (T_C = 25°C, Package Limited)		100	A
Continuous Drain Current (T_C = 100°C)		75	A
Continuous Drain Current (T_A = 25°C) *1		23	A
Continuous Drain Current (T_A = 100°C) *1		15	A
Pulsed Drain Current (t_p =10μs, T_C = 25°C)	I_{DM}	400	A
Single Pulse Avalanche Energy *3	E_{AS}	100	mJ
Power Dissipation (T_C = 25°C)	P_D	78	W
Operating Junction Temperature Range	T_J	-55 ~ +150	°C
Storage Temperature Range	T_{STG}	-55 ~ +150	°C

Thermal Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit
Thermal Resistance Junction-to-Case	$R_{\theta JC}$	-	1.3	1.6	°C/W
Thermal Resistance Junction-to-Air *1	$R_{\theta JA}$	-	30	40	°C/W

Electrical Characteristics (@ T_J = 25°C unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
Static Characteristics						
V_{DSS}	Drain-Source Breakdown Voltage	V_{GS} = 0V, I_D = 250μA	40	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS} = 40V, V_{GS} = 0V	-	-	1	μA
I_{GSS}	Gate-Body Leakage Current	V_{GS} = ±20V, V_{DS} = 0V	-	-	±100	nA
On Characteristics						
$R_{DS(ON)}$	Drain-Source On-resistance *2	V_{GS} = 10V,I_D = 20A	-	2.8	3.5	mΩ
		V_{GS} = 4.5V,I_D = 20A	-	4.0	5.5	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS} = V_{GS}, I_D = 250μA	1	1.7	2.5	V
R_G	Gate Resistance	V_{GS} = 0V, f = 1MHz	-	4.7	-	Ω
Dynamic Characteristics						
C_{ISS}	Input Capacitance	V_{GS} = 0V V_{DS} = 20V f = 1.0MHz	-	1685	-	pF
C_{OSS}	Output Capacitance		-	647	-	
C_{RSS}	Reverse Transfer Capacitance		-	9	-	
Switching Characteristics						
$t_{d(ON)}$	Turn-on Delay Time *4	V_{DD} = 20V V_{GS} = 10V R_G = 6Ω R_L = 1Ω	-	9	-	ns
t_r	Turn-on Rise Time *4		-	51	-	
$t_{d(OFF)}$	Turn-Off Delay Time *4		-	46	-	
t_f	Turn-Off Fall Time *4		-	78	-	
Q_G	Total Gate-Charge	V_{DD} = 20V V_{GS} = 10V I_D = 20A	-	27	-	nC
Q_{GS}	Gate to Source Charge		-	4.5	-	
Q_{GD}	Gate to Drain (Miller) Charge		-	5	-	
Source-Drain Diode Characteristics						
V_{SD}	Diode Forward Voltage *2	I_S = 20A, V_{GS} = 0V	-	0.8	1.2	V
trr	Reverse Recovery Time	I_S = 20A, V_{GS} = 0V di/dt = 100A/μs	-	65	-	ns
Qrr	Reverse Recovery Charge		-	66	-	nC

Notes:

1. The data tested by surface mounted on a 1 inch^2 FR-4 board with 2OZ copper
2. The data tested by pulsed, pulse width ≤ 300μs, duty cycle ≤ 2%
3. The E_{AS} data shows Max. rating. The test condition is V_{DD} = 20V, V_{GS} = 10V, L = 0.5mH
4. Guaranteed by design, not subject to production

Ratings and Characteristics Curves (@ T_A = 25°C unless otherwise specified)

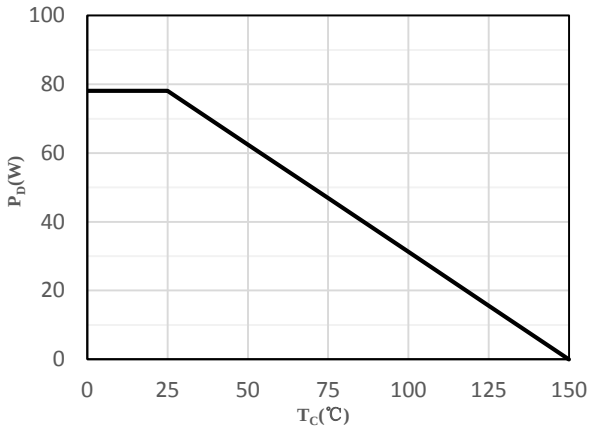


Fig 1 Power Dissipation

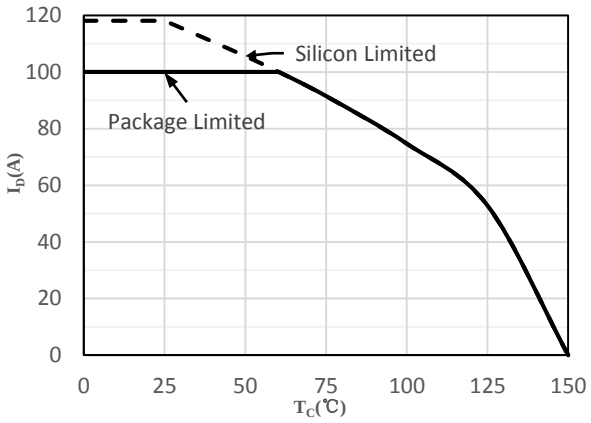


Fig 2 Drain Current

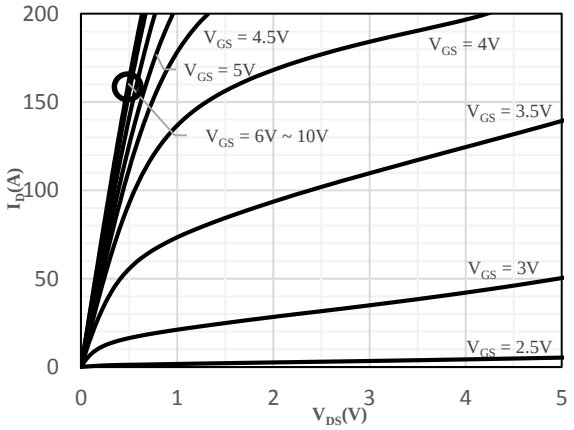


Fig 3 Typical Output Characteristics

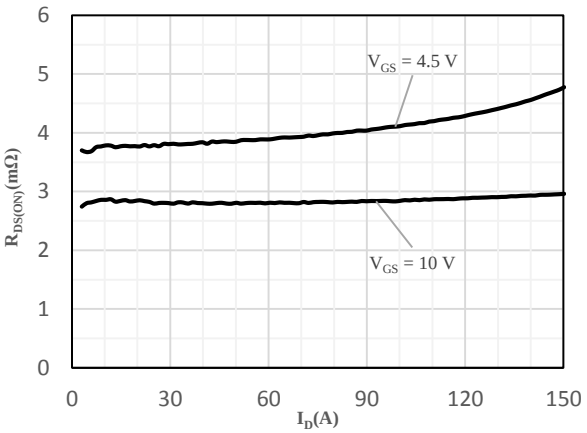


Fig 4 On-Resistance vs. Drain Current and Gate Voltage

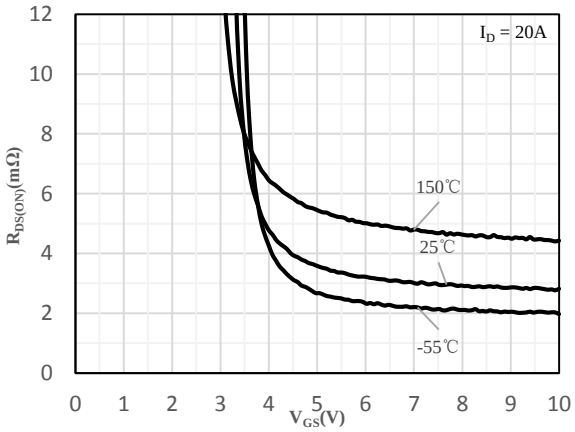


Fig 5 On-Resistance vs. Gate-Source Voltage

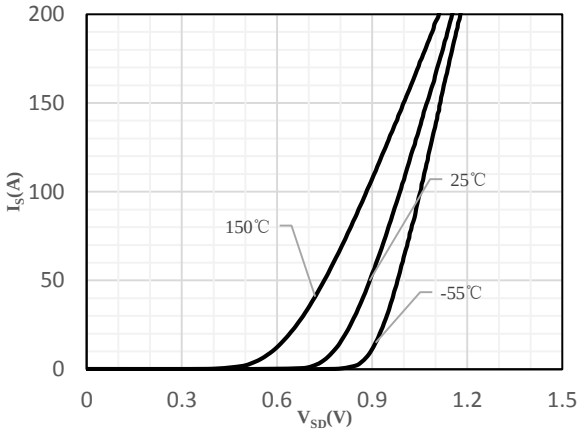


Fig 6 Body-Diode Characteristics

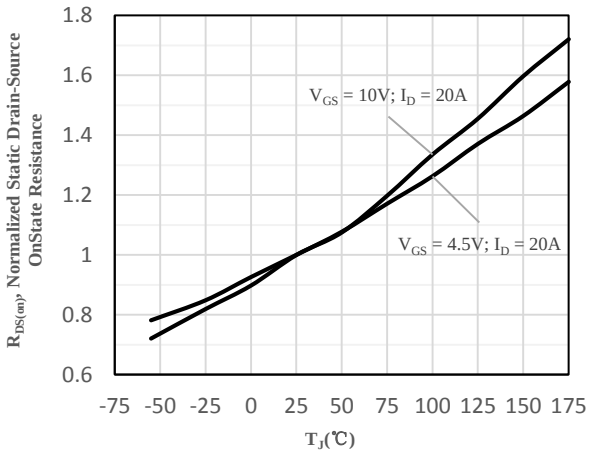


Fig 7 Normalized On-Resistance vs. Junction Temperature

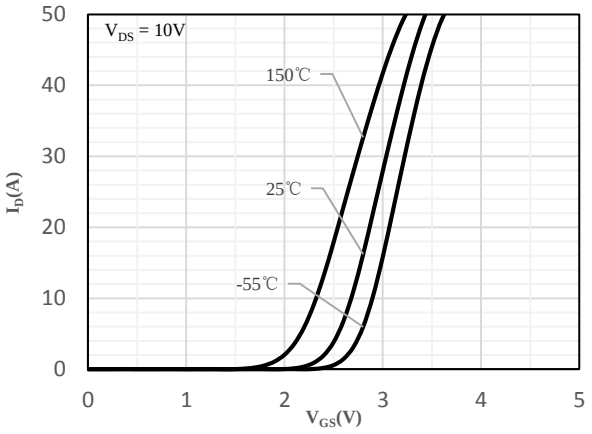


Fig 8 Transfer Characteristics

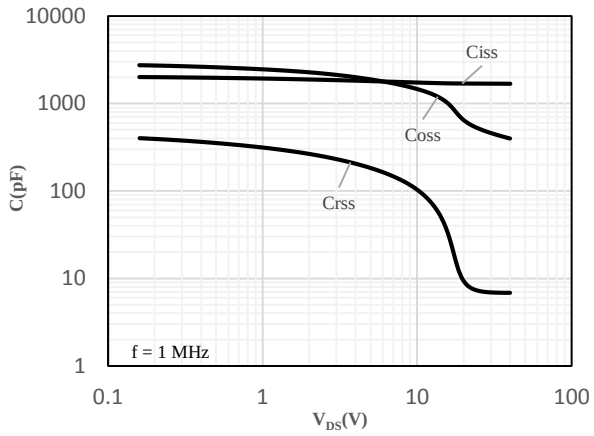


Fig 9 Capacitance Characteristics

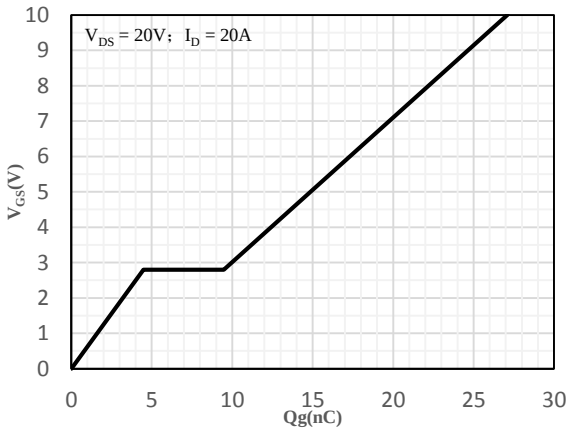


Fig 10 Gate-Charge Characteristics

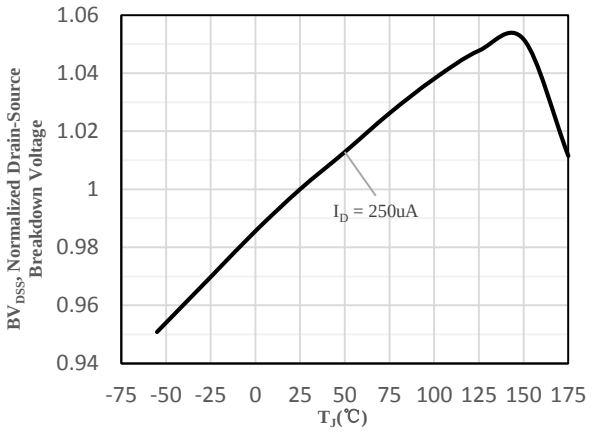


Fig 11 Normalized Breakdown Voltage vs. Junction Temperature

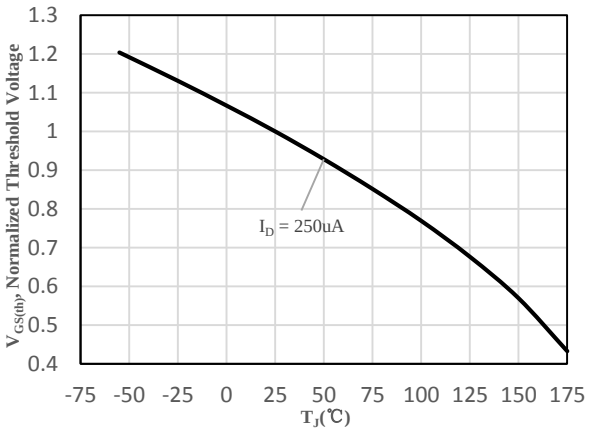


Fig 12 Normalized $V_{GS(th)}$ vs. Junction Temperature

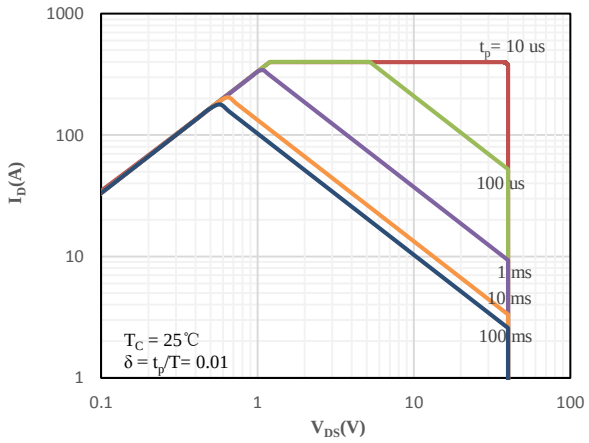


Fig 13 Safe Operation Area

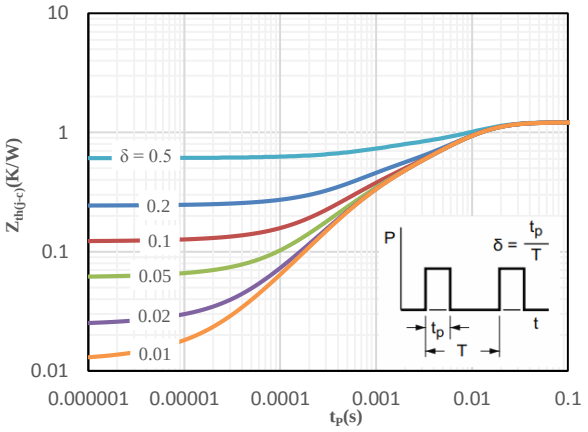
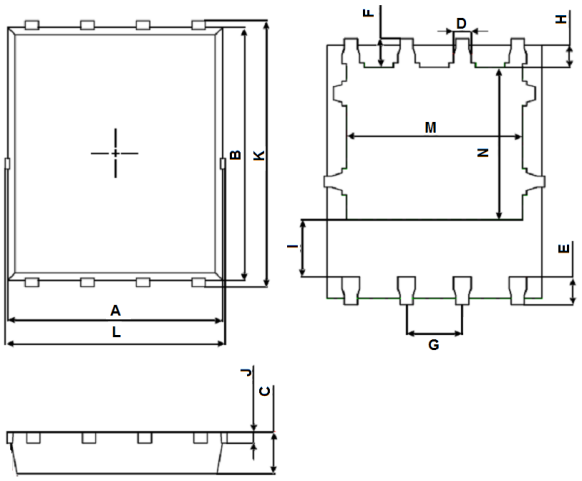


Fig 14 Maximum transient thermal impedance

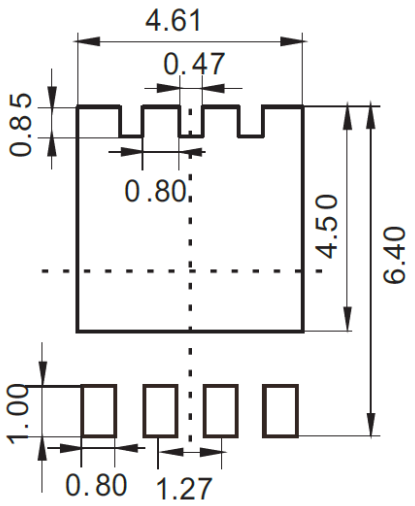
Package Outline Dimensions (Unit: mm)



PDFN5×6-8L		
Dimension	**Min.**	**Max.**
A	4.824	4.976
B	5.674	5.826
C	0.900	1.000
D	0.350	0.450
E	0.559	0.711
F	0.574	0.726
G	1.250	1.290
H	0.424	0.576
I	1.190	1.390
J	0.154	0.354
K	5.974	6.126
L	4.944	5.096
M	3.910	4.110
N	3.375	3.575

Mounting Pad Layout (Unit: mm)

PDFN5×6-8L



IMPORTANT NOTICE

Changzhou Galaxy Century Microelectronics (GME) reserves the right to make changes without further notice to any product information (copyrighted) herein to make corrections, modifications, improvements, or other changes. GME does not assume any liability arising out of the application or use of any product described herein; neither does it convey any license under its patent rights, nor the rights of others.